# 4 Channel EMI Pi-Filter Array with ESD Protection +4 ESD Diodes

This device is a 4 channel EMI filter array for data lines. Greater than -40 dB attenuation is obtained at frequencies from 800 MHz to 2.2 GHz. It also offers ESD protection – clamping transients from static discharges to protect delicate data line circuitry. It is offered in 300  $\mu$ m and 350  $\mu$ m solder spheres.

#### **Features**

- EMI Filtering and ESD Protection for Data Lines
- Integration of 26 Discretes Offers Cost and Space Savings
- Exceeds IEC61000-4-2 (Level 4) Specifications
- Low Profile Flip-Chip Packaging
- MSL 1
- 300 µm Solder Spheres (NUF4105), Case 499D

# **Typical Applications**

- EMI Filtering and ESD Protection for Data Lines
- Cell Phones
- Handheld Portables
- Notebook Computers
- MP3 Players

## **MAXIMUM RATINGS** $(T_A = 25^{\circ}C)$

| Rating  | Symbol           | Value          | Unit |
|---|------------------|----------------|------|
| ESD Discharge IEC61000–4–2,  – Air Discharge  – Contact Discharge  Human Body Model | V <sub>PP</sub>  | 30<br>30<br>16 | kV   |
| DC Power per Resistor   | $P_{R}$          | 100            | mW   |
| DC Power per Package  | P <sub>T</sub>   | 400            | mW   |
| Junction Temperature  | TJ               | 150            | °C   |
| Operating Temperature Range   | T <sub>op</sub>  | -40 to +85     | °C   |
| Storage Temperature Range   | T <sub>stg</sub> | -55 to +150    | °C   |

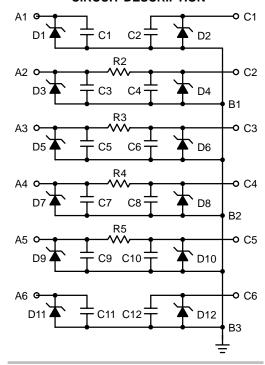
Maximum ratings are those values beyond which device damage can occur. Maximum ratings applied to the device are individual stress limit values (not normal operating conditions) and are not valid simultaneously. If these limits are exceeded, device functional operation is not implied, damage may occur and reliability may be affected.



# ON Semiconductor®

http://onsemi.com

#### CIRCUIT DESCRIPTION





FLIP-CHIP CASE 499D 300 µm Bumps

#### **DEVICE MARKING**

NUF4105YYWW

YY = Year WW = Work Week

## ORDERING INFORMATION

| Device      | Package   | Shipping <sup>†</sup> |
|-------------|-----------|-----------------------|
| NUF4105FCT1 | Flip-Chip | 3000/Tape & Reel      |

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specification Brochure, BRD8011/D.

# **ELECTRICAL CHARACTERISTICS** (T<sub>A</sub> = 25°C unless otherwise noted)

| Symbol            | Characteristic                        | Min | Тур | Max | Unit |
|-------------------|---------------------------------------|-----|-----|-----|------|
| $V_{BR}$          | $I_Z = 10 \text{ mA}$                 | 6.0 | 7.0 | 8.0 | V    |
| I <sub>R</sub>    | V <sub>RM</sub> = 3.3 V per line      | -   | -   | 0.1 | μΑ   |
| R <sub>I/O</sub>  | $I_R = 20 \text{ mA}$                 | 80  | 100 | 120 | Ω    |
| C <sub>line</sub> | $V_{R=} 2.5 V$ , f = 1.0 MHz (Note 1) | -   | 53  | -   | pF   |

<sup>1.</sup> Measured from input/output pins to ground.

## TYPICAL PERFORMANCE CURVES

 $(T_A = 25^{\circ}C \text{ unless otherwise specified})$ 

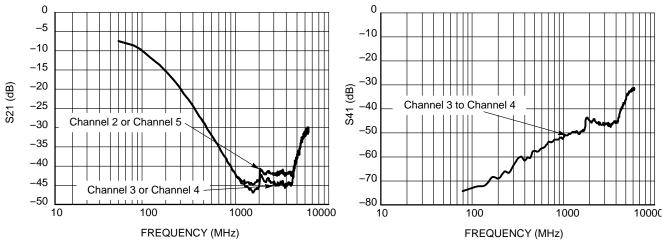


Figure 1. Insertion Loss Curve

Figure 2. Analog Crosstalk Curve

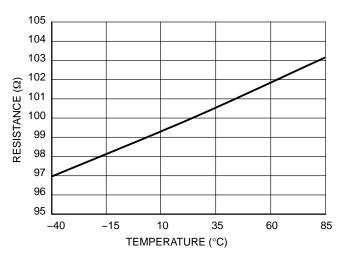


Figure 3. Resistance Over Temperature

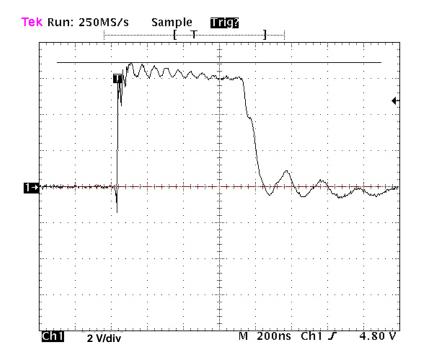


Figure 4. ESD Response for Human Body Model (+8.0 kV)

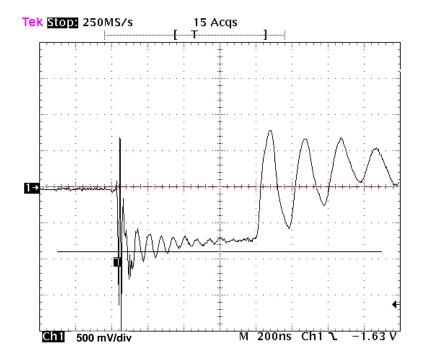


Figure 5. ESD Response for Human Body Model (-8.0 kV)

# **Printed Circuit Board Recommendations**

| Parameter                | 500 μm Pitch<br>300 or 350 μm Solder Ball |
|--------------------------|---|
| PCB Pad Size             | 250 μm +25<br>–0                          |
| Pad Shape                | Round                                     |
| Pad Type                 | NSMD                                      |
| Solder Mask Opening      | 350 μm ±25                                |
| Solder Stencil Thickness | 125 μm                                    |
| Stencil Aperture         | 250 x 250 μm sq.                          |
| Solder Flux Ratio        | 50/50                                     |
| Solder Paste Type        | No Clean Type 3 or Finer                  |
| Trace Finish             | OSP Cu                                    |
| Trace Width              | 150 μm Max                                |

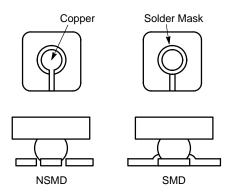


Figure 6. Solder Mask versus Non-Solder Mask Definition

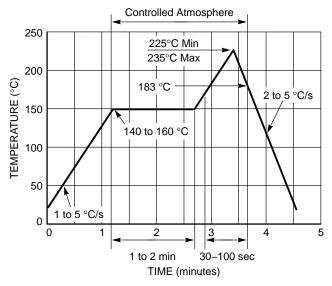
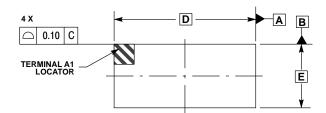
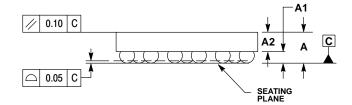


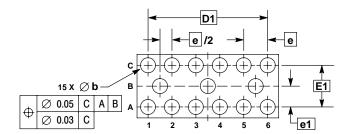
Figure 7. Solder Reflow Profile

# **PACKAGE DIMENSIONS**

# 15 PIN FLIP-CHIP CSP CASE 499D-01 ISSUE O







- NOTES:
  1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
  2. CONTROLLING DIMENSION: MILLIMETER.
  3. COPLANARITY APPLIES TO SPHERICAL CROWNS OF SOLDER BALLS.

|     | MILLIMETERS |       |  |
|-----|-------------|-------|--|
| DIM | MIN         | MAX   |  |
| Α   |             | 0.700 |  |
| A1  | 0.210       | 0.270 |  |
| A2  | 0.380       | 0.430 |  |
| D   | 2.960 BSC   |       |  |
| Е   | 1.330 BSC   |       |  |
| b   | 0.290       | 0.340 |  |
| е   | 0.500 BSC   |       |  |
| e1  | 0.435 BSC   |       |  |
| D1  | 2.500       | BSC   |  |
| E1  | 0.870       | BSC   |  |

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